

Tailoring Materials for Solar Energy Conversion Applications

Anca Duta

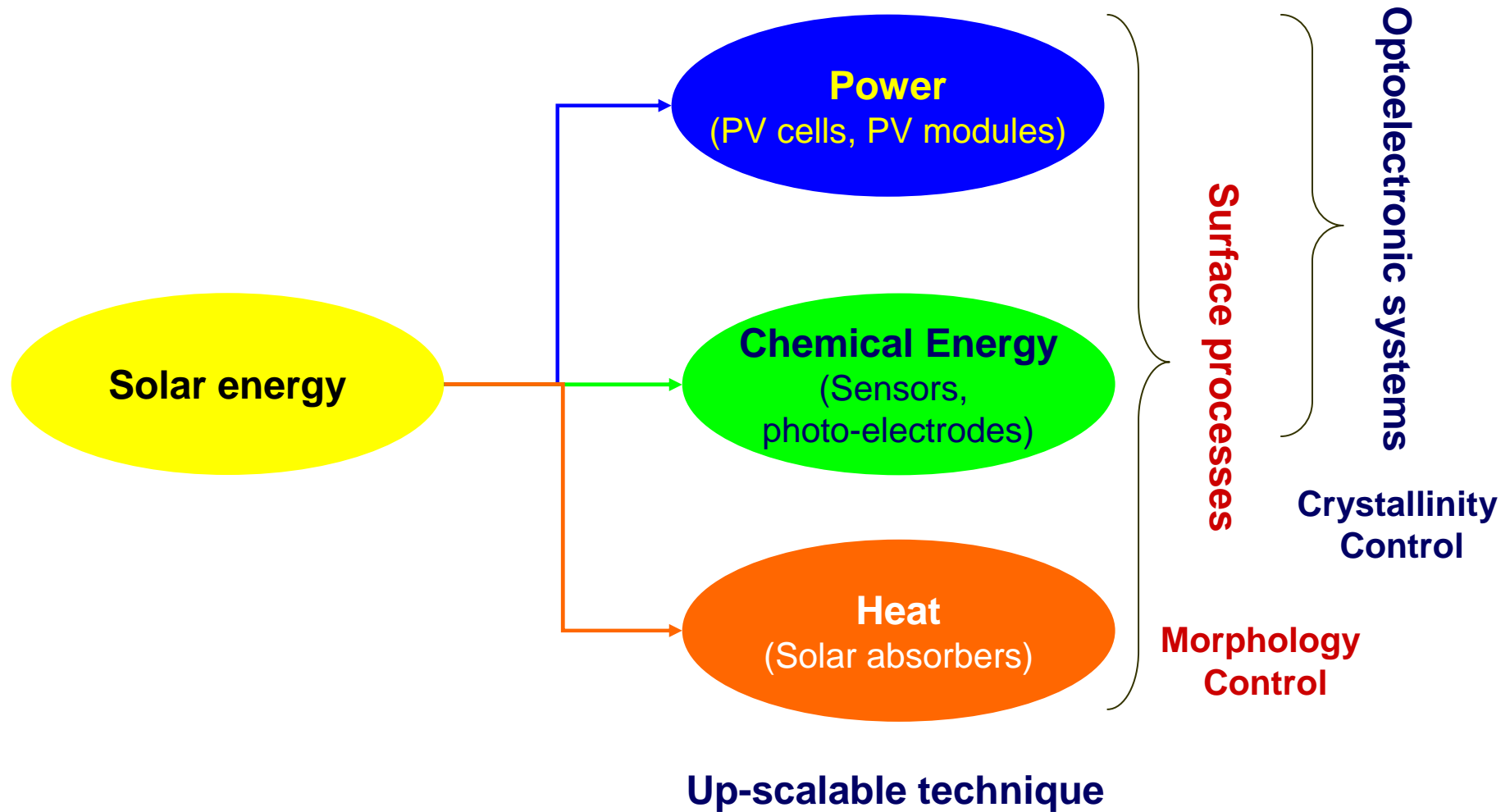
Alexandru Enesca, Mihaela Dudita, Maria Visa, Luminita Andronic, Dana Perniu

“Transilvania” University of Brasov

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Materials for solar energy conversion devices

Metal Oxide Semiconductors



Department: Renewable Energy Systems and Recycling

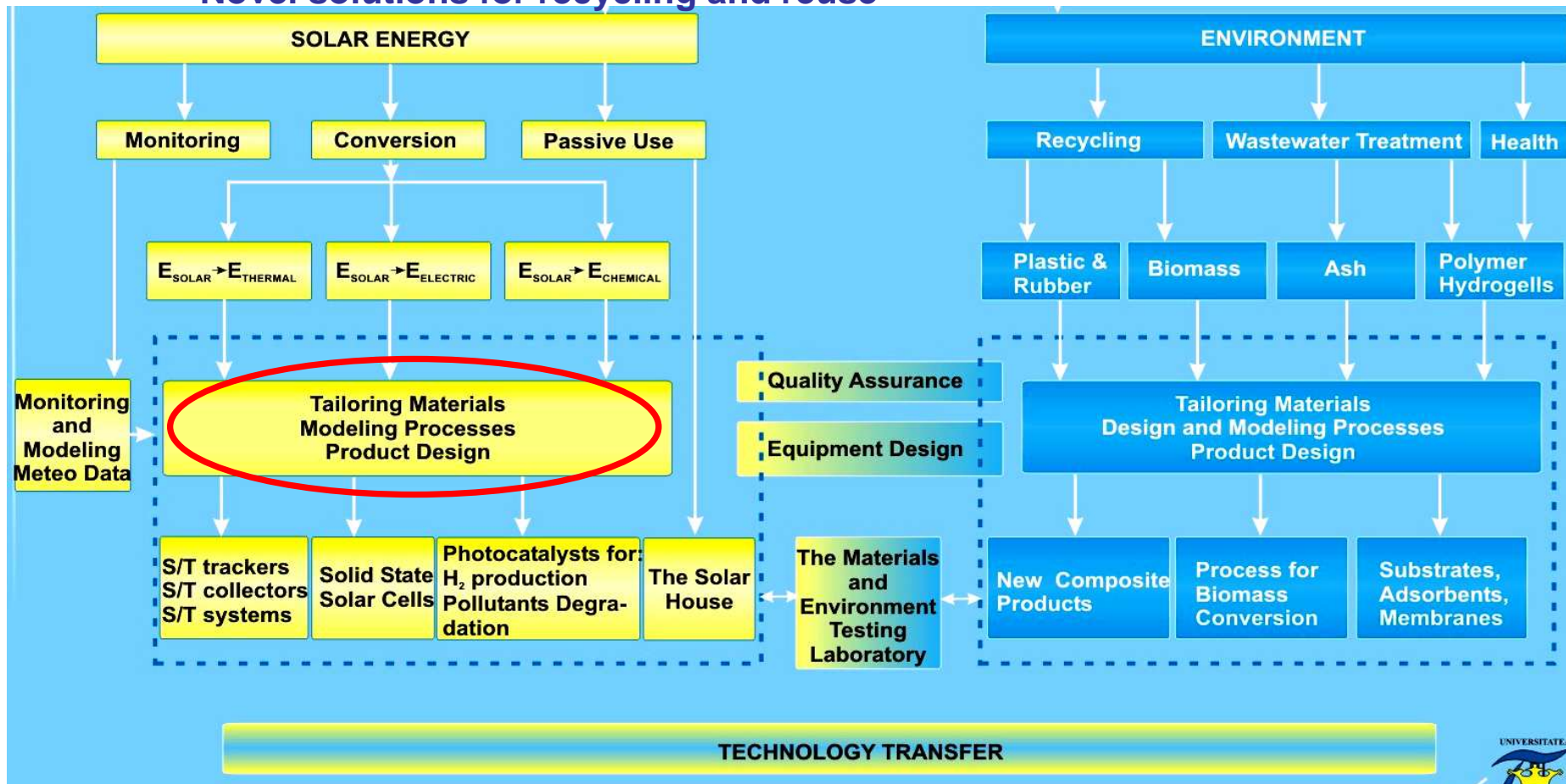
Our approach: Integrated Product Design

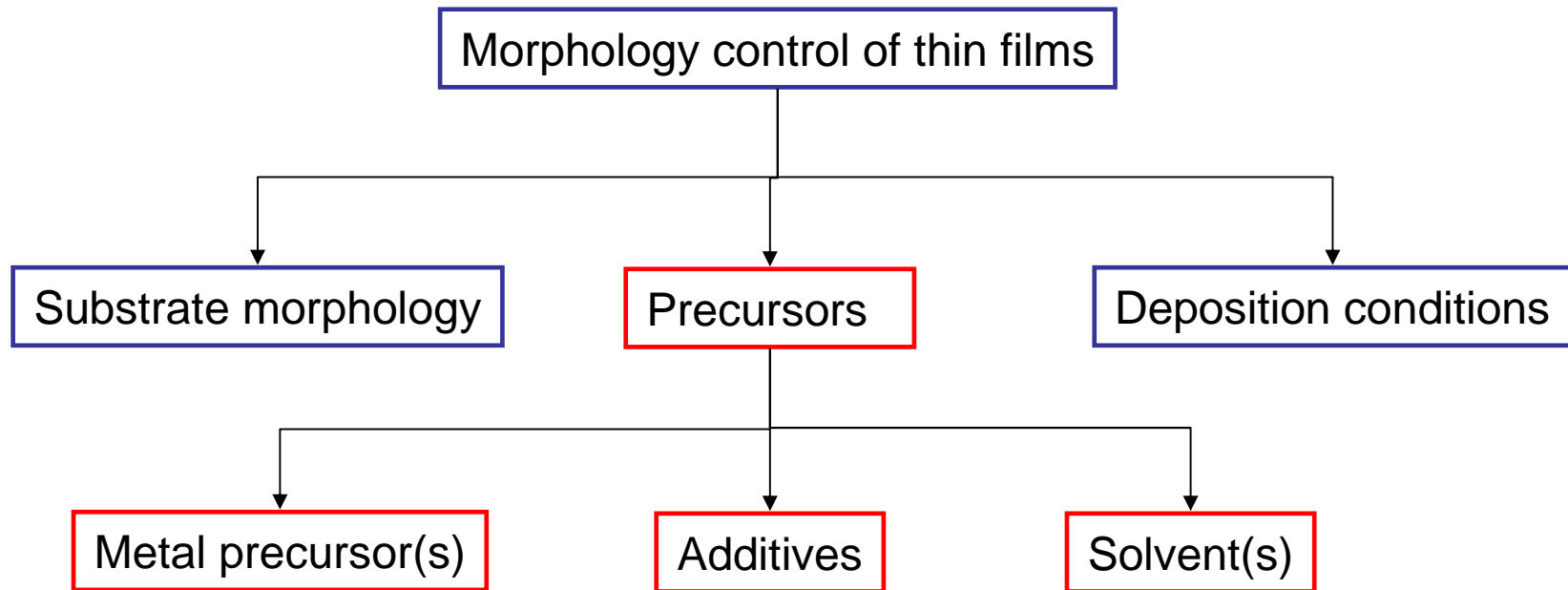
→ Developing materials for targeted applications

Research areas:

Increasing the efficiency of solar energy conversion

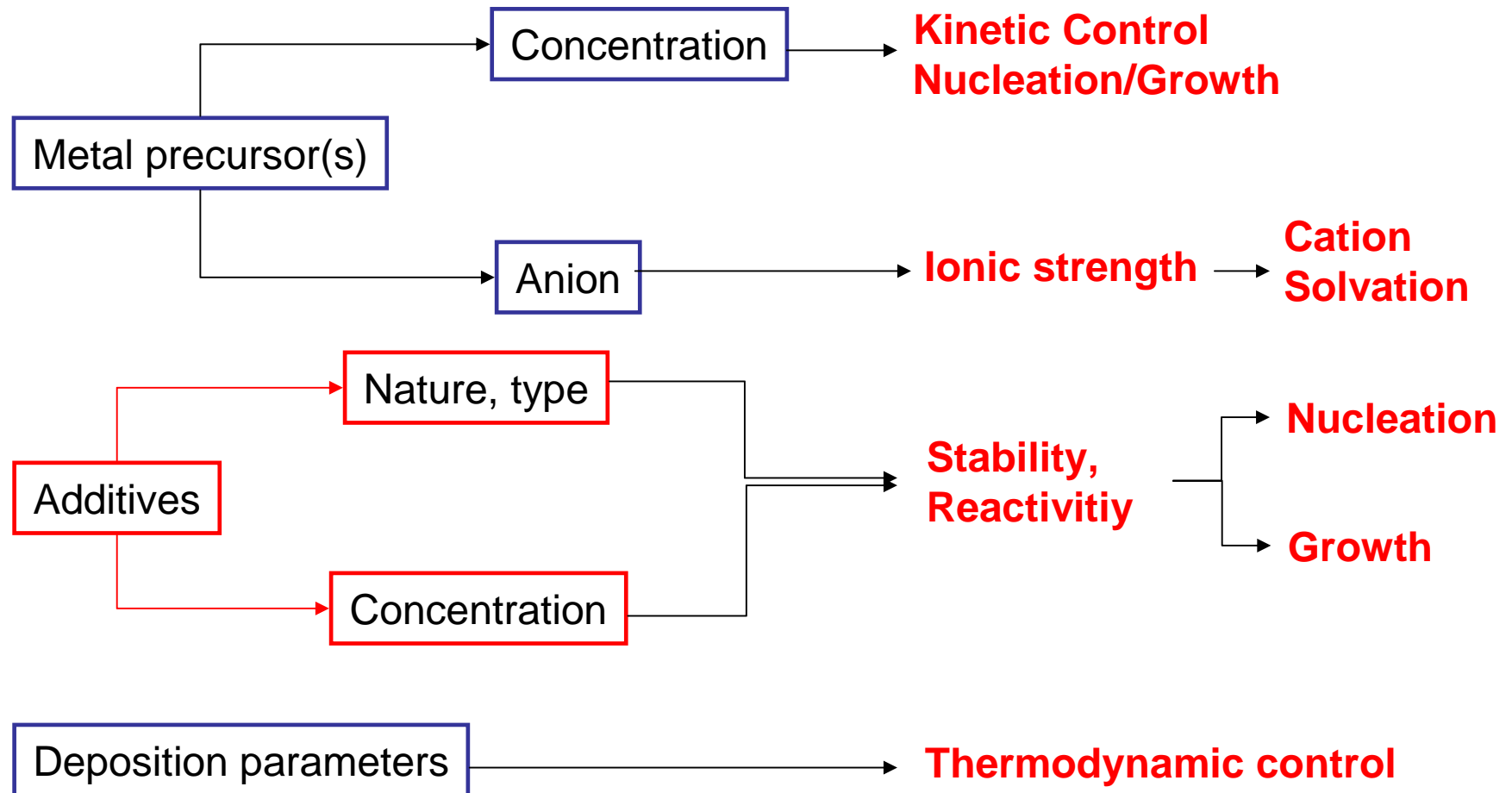
Novel solutions for recycling and reuse



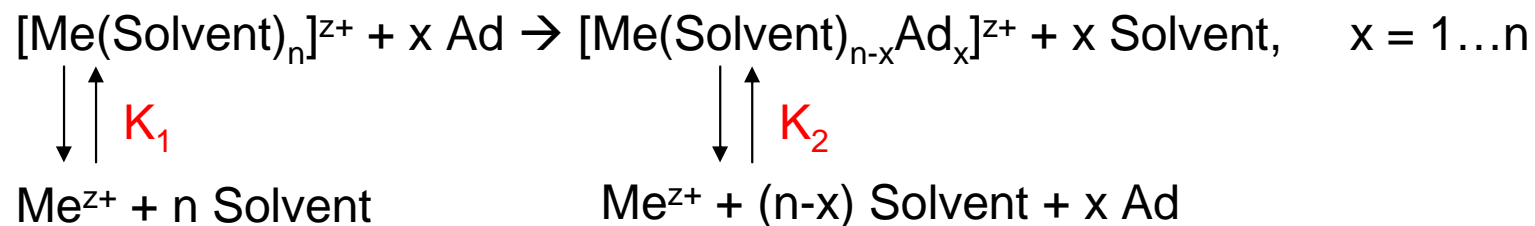


Deposition techniques: up-scalable, suitable for large surface areas
Spray Pyrolysis Deposition (SPD)

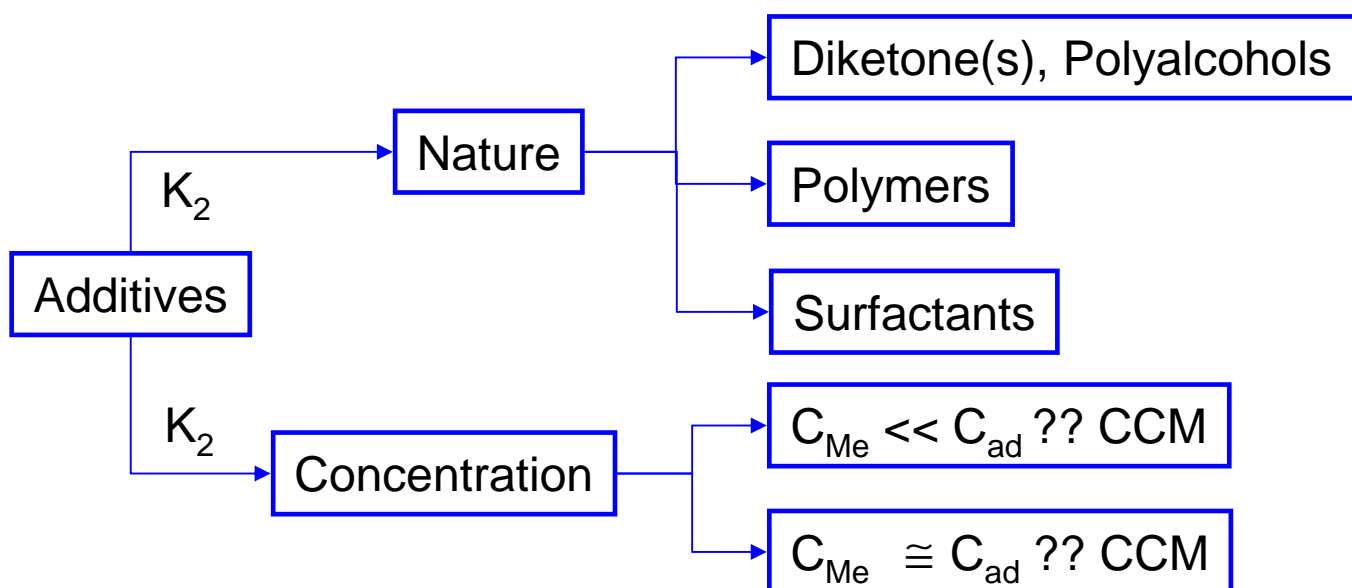
Mechanisms of morphology control in thin films of metal oxide semiconductors



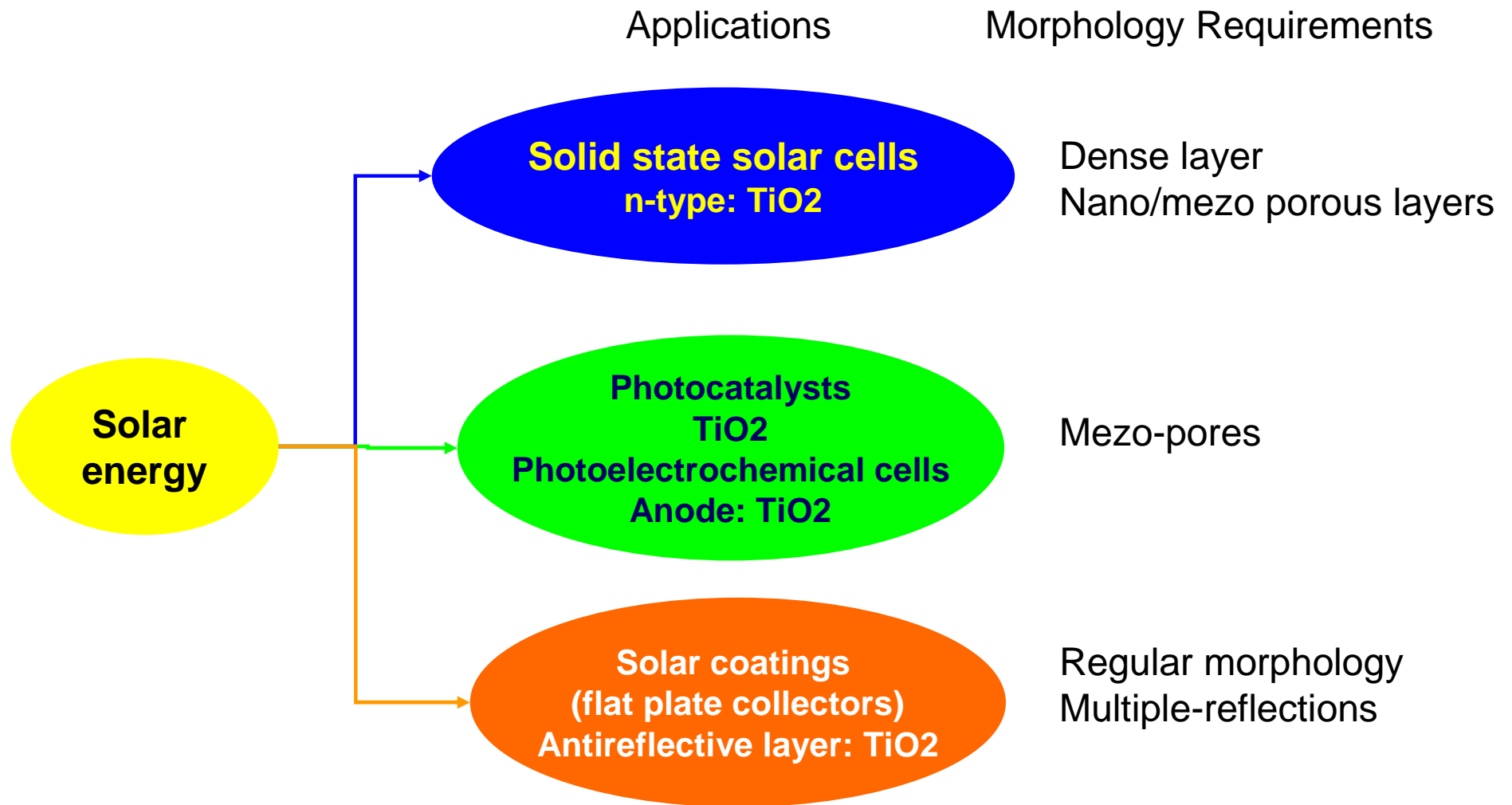
Mechanisms of morphology control in thin films of metal oxide semiconductors\ Additives: interaction with the precursor metal cation



Observation: K_1 is fixed; K_2 can be modified/controlled (by changing x)

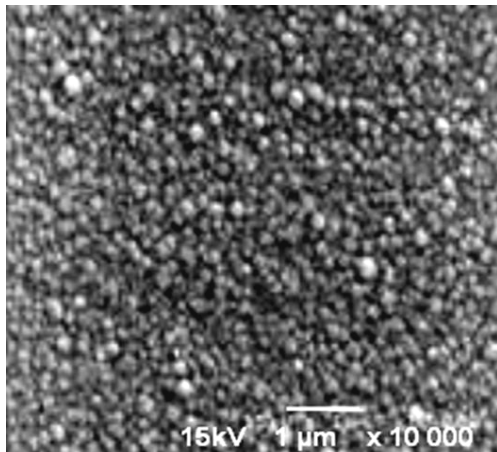
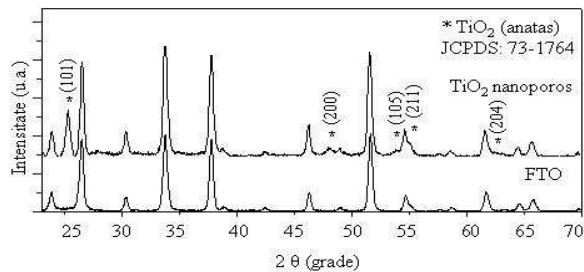


Case study: TiO₂ (anatase)

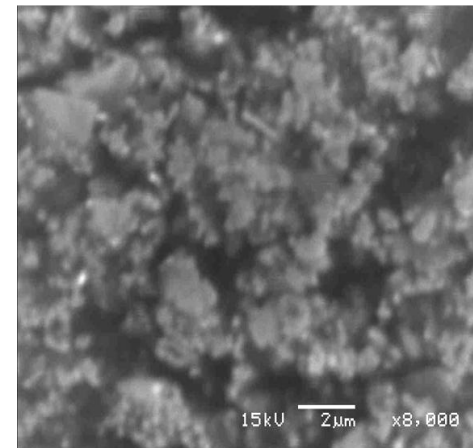
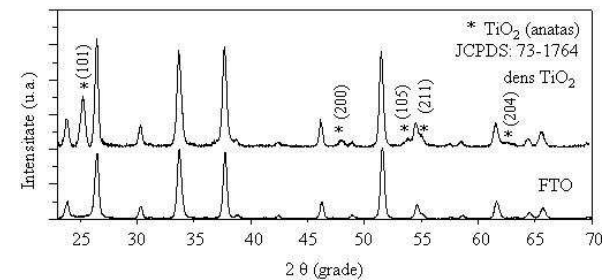


Thermodynamic control in SPD Deposition T, P

Homogeneous growth (dense films, small grains):
excess of **complexing** aditiv (AcAc)



Dense thin film:
TTIP: AcAc: EtOH = 1: 1.5: 22.5
T = 350°C

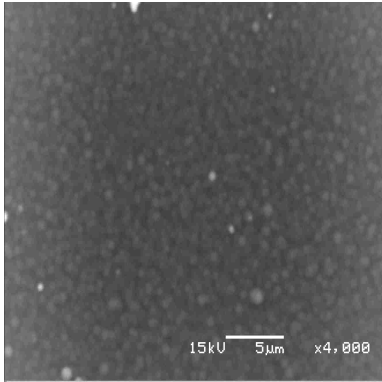


Nano/mezo porous thin film:
TTIP: AcAc: EtOH = 1.3: 1: 20.8
T = 400°C

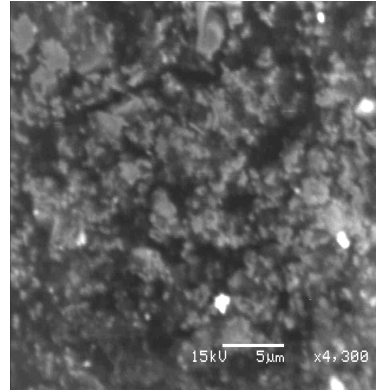
Precursor: **TTIP**
Additive: **Acetylacetone (AcAc)**
Solvent: **Ethanol (EtOH)**

Morphology control:
Composition
Temperature

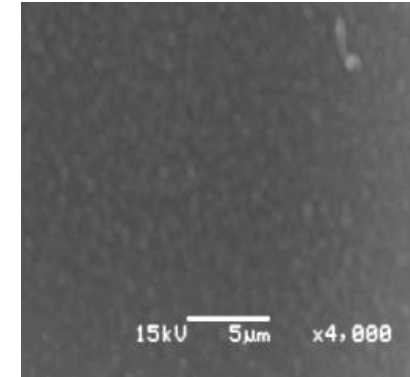
Thermodynamic control in SPD Deposition T, P



P = 0.8 bar



P = 1.2 bar



P = 1.4 bar

Precursor: TTIP

Additive: Acetylacetone (AcAc)

Solvent: Ethanol (EtOH)

Morphology control:

Composition

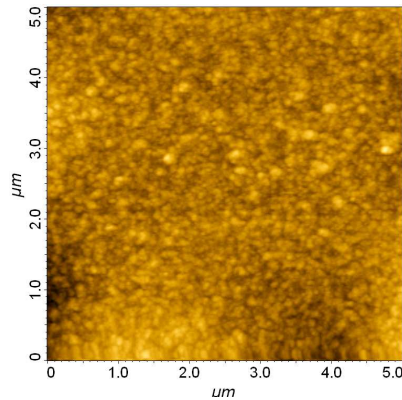
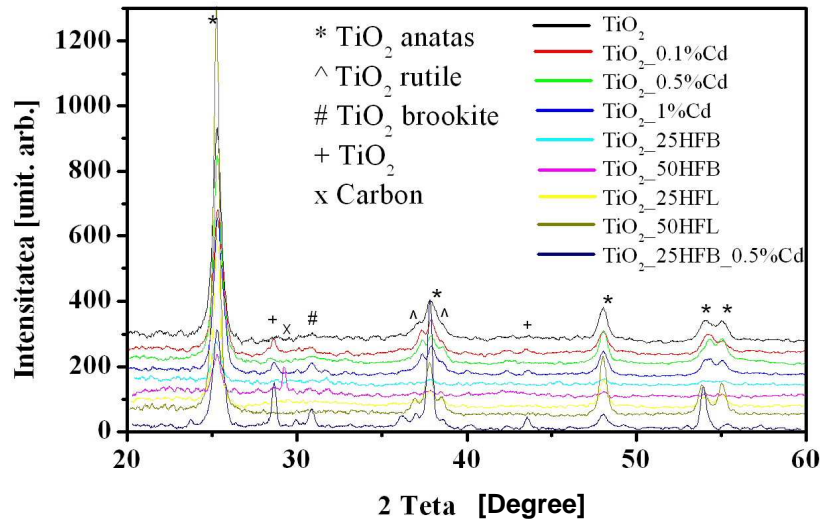
Pressure

TTIP: AcAc: EtOH: 1.3: 1: 20.8

T = 400°C

Kinetic control in SPD

Additives: Polymeric additives



a)

- a) TiCl_4 (in Ethanol) 0.05M, 400°C
- b) TiCl_4 (EtOH), 0.05M, 25ppm HFL, 400°C
- c) TiCl_4 (EtOH), 0.05M, 25ppm HFB, 0.5%Cd, 400°C

Homogeneous growth, various aspect ratio:
Very low amount of **tailored** additives
(weak interactions)

Precursor: TiCl_4

Additives:

Hydrophobic polymer, HFB

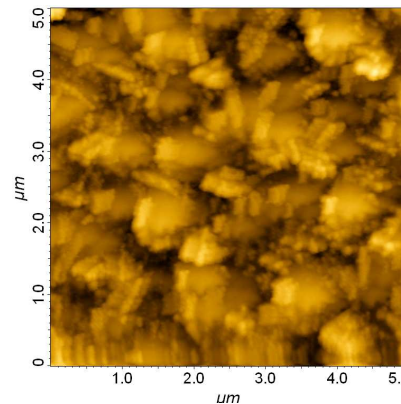
Hydrophilic polymer, HFL

Solvent: Ethanol

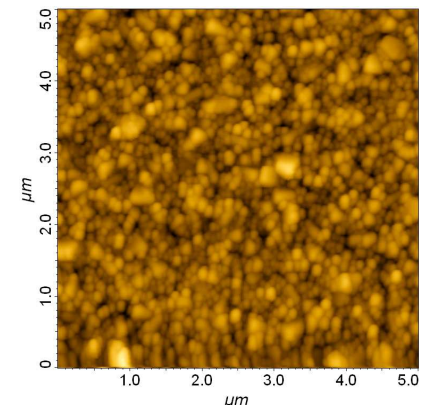
Morphology control:

Additive type

Doping



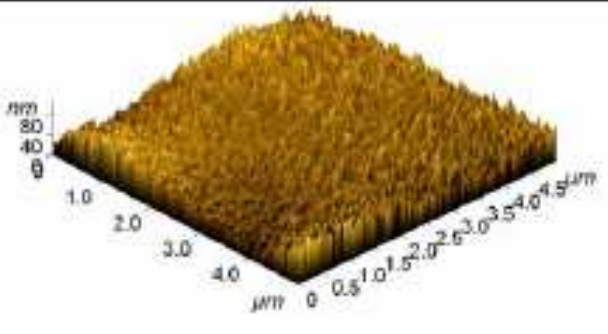
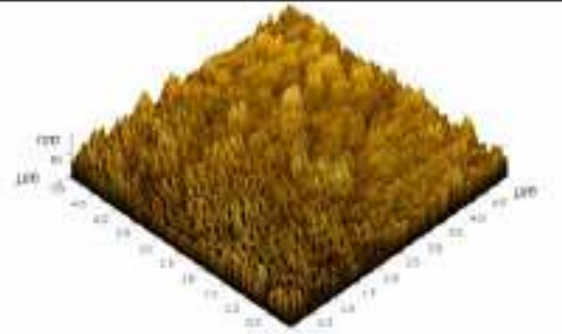
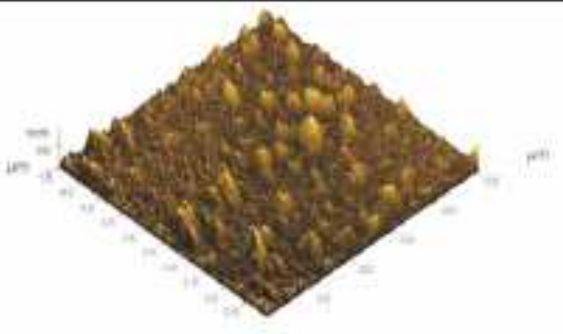

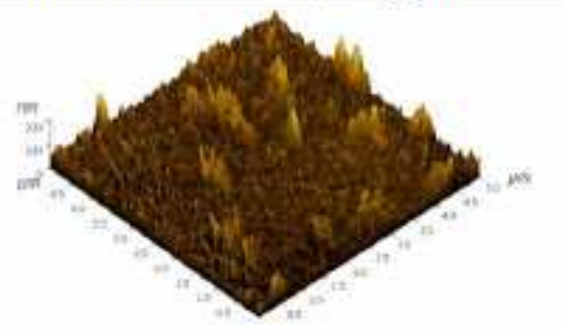

b)



c)

Kinetic control in SPD

Additives: Nonionic surfactants (Decanol, Hexadecanol)

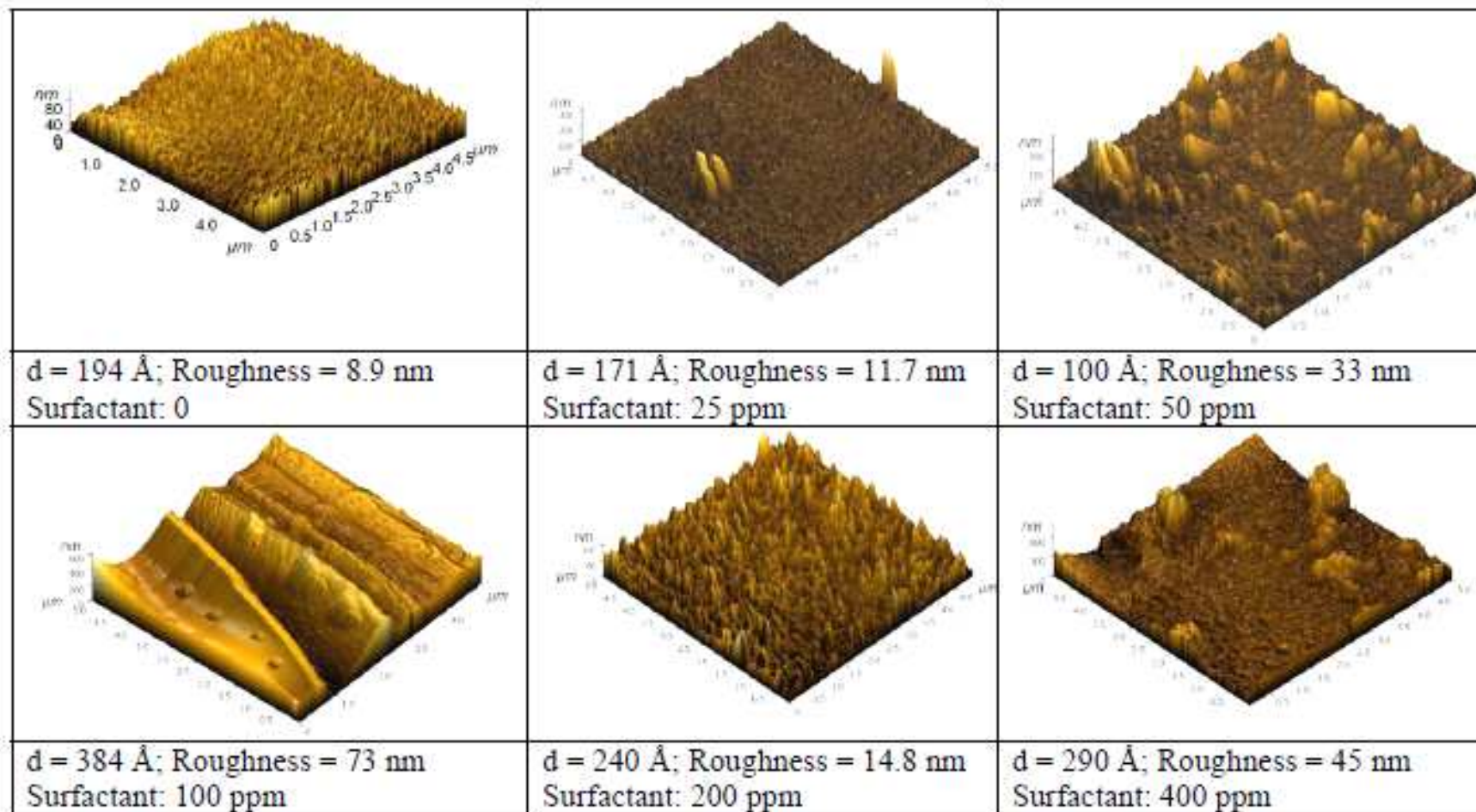
		
$d = 194 \text{ \AA}$; Roughness = 8.9 nm Surfactant: 0	$d = 81 \text{ \AA}$; Roughness = 12.8 nm Surfactant: decanol, 50ppm	$d = 100 \text{ \AA}$; Roughness = 29 nm Surfactant: decanol, 400 ppm
		
$d = 211 \text{ \AA}$; Roughness = 71 nm Surfactant: hexadecanol, 25ppm	$d = 196 \text{ \AA}$; Roughness = 17.2 nm Surfactant: hexadecanol, 50ppm	$d = 184 \text{ \AA}$; Roughness = 18 nm Surfactant: hexadecanol, 400 ppm

Precursor: TiCl_4 (in Ethanol) 0.05M

Temperature: 400°C

Kinetic control in SPD

Additives: Cationic surfactant (hexadecyl-trimethyl-ammonium bromide)

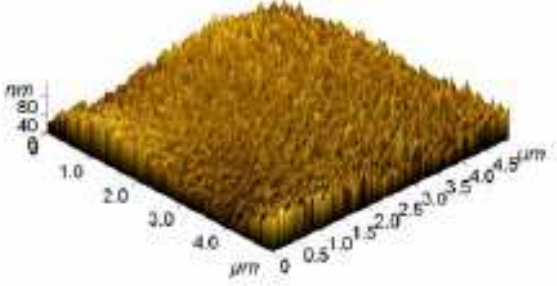

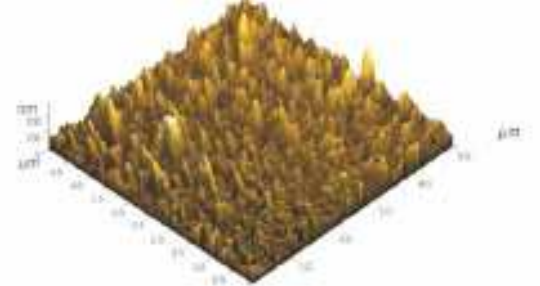


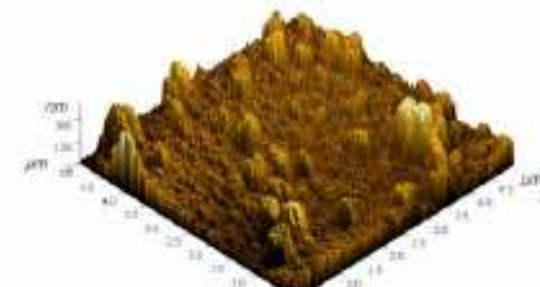


Precursor: TiCl_4 (in Ethanol) 0.05M

Temperature: 400°C

Kinetic control in SPD

Additives: Anionic (sodium-dodecyl-sulfate)

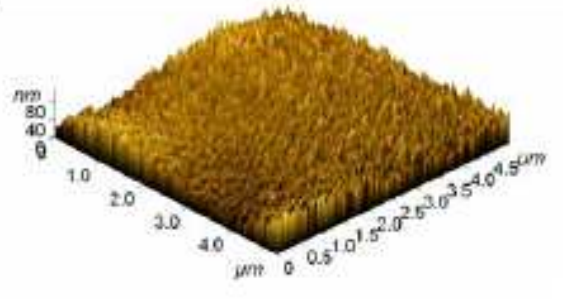
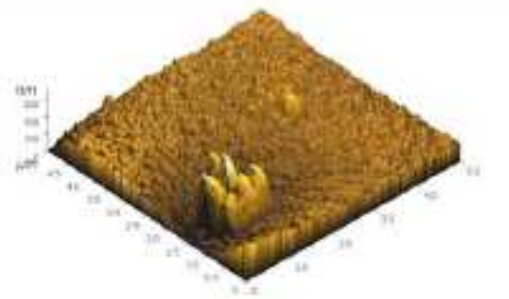

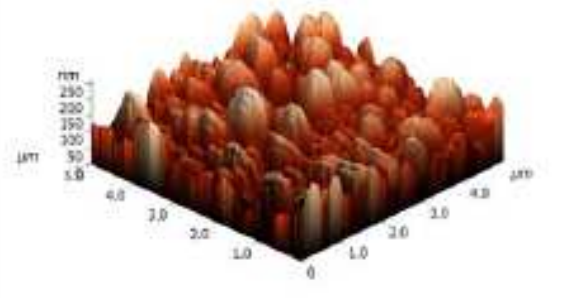
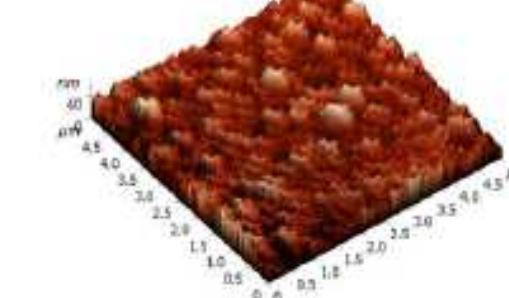

		
$d = 194 \text{ \AA}$; Roughness = 8.9 nm Surfactant: 0	$d = 274 \text{ \AA}$; Roughness = 42 nm Surfactant: 25 ppm	$d = 88 \text{ \AA}$; Roughness = 29 nm Surfactant: 50 ppm
		
$d = 479 \text{ \AA}$; Roughness = 21 nm Surfactant: 100 ppm	$d = 149 \text{ \AA}$; Roughness = 45 nm Surfactant: 200 ppm	$d = 189 \text{ \AA}$; Roughness = 41 nm Surfactant: 400 ppm

Precursor: TiCl_4 (in Ethanol) 0.05M

Temperature: 400°C

Kinetic control in SPD

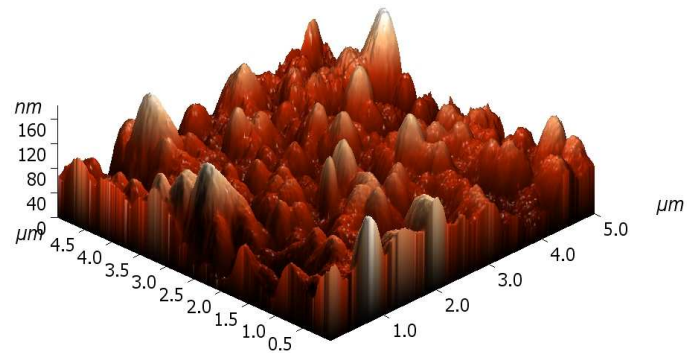
Additives: Anionic (sodium-dodecyl-sulfate)

		
<p>Precursor: TiCl_4 Surfactant: 0</p>	<p>Precursor: TiCl_4 Surfactant: 25 ppm</p>	<p>Precursor: TiCl_4 Surfactant: 100 ppm</p>
		
<p>Precursor: TTIP Surfactant: 0</p>	<p>Precursor: TTIP Surfactant: 25 ppm</p>	<p>$d = 189 \text{ \AA}$; Roughness = 41 nm Surfactant: 400 ppm</p>

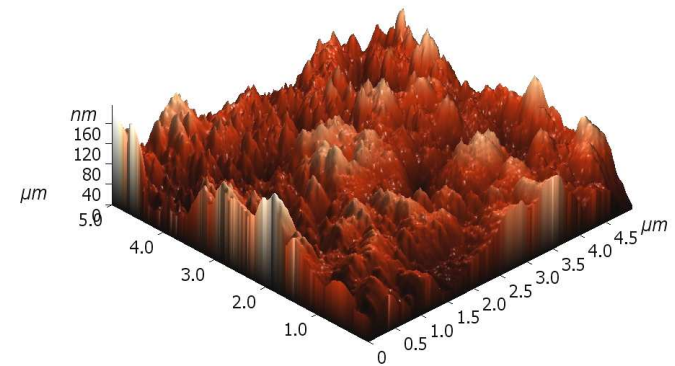
Temperature: 400°C

Similar results for p-type semiconductor CuInS₂ (CIS)

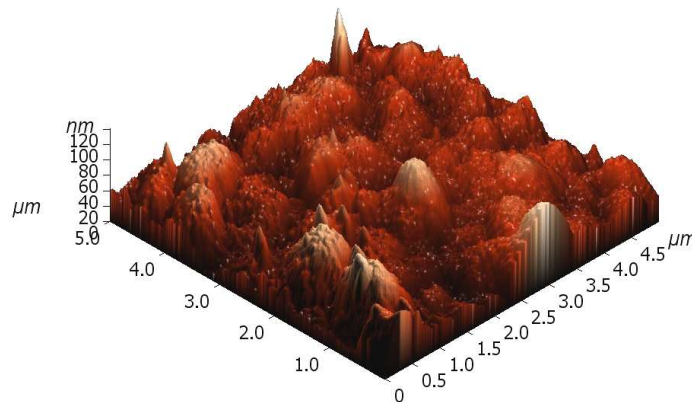
Surfactant: sodium-dodecyl-sulfate



Surfactant: 0 ppm



Surfactant: 50 ppm



Surfactant: 70 ppm

Conclusion:

There's plenty of room at the bottom!

Richard Feynman, 1960